

**In the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.-4. (Cancelled)

5. (Previously presented) An electronic circuit unit comprising thin film circuit elements including conducting patterns formed on an alumina substrate, a plurality of thin film capacitors formed on the alumina substrate so as to be connected to the conducting patterns, resistors, and inductance elements and a semiconductor bare chip having a transistor wire-bonded to the conducting patterns, wherein the conducting pattern has a connection land connected to an electrode of the transistor to be grounded in a high frequency band, the capacitor has a plurality of ground capacitors grounded in the high frequency band, and one electrode of each of the plurality of capacitors is connected to the ground conducting pattern and the other electrode of each of the plurality of capacitors is connected to the connection land through the conducting patterns that are separated from each other.

6. (Original) The electronic circuit unit according to claim 5, wherein the plurality of ground capacitors are different from each other in size.

7. (Previously presented) The electronic circuit unit according to claim 5, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

8. (Previously presented) The electronic circuit unit according to claim 6, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

9.-11. (Cancelled)

12.-14. (Not entered)

15. (New) An electronic circuit unit comprising:  
an alumina substrate;  
thin film circuit elements including capacitors, resistors, and inductance elements formed on the alumina substrate;  
thin film conducting patterns connected to the circuit elements formed on the alumina substrate;  
a semiconductor bare chip mounted on the alumina substrate and wire bonded to the conducting pattern; and  
a ground conducting pattern formed on and at least partially covering the alumina substrate,  
wherein at least one of the capacitors is a ground capacitor comprised of an upper electrode disposed on a surface of a dielectric material, the dielectric material is formed on the ground conducting pattern, and a perimeter of the upper electrode is a polygon with greater than four sides.

16. (New) The electronic circuit unit according to claim 15, wherein a part of the ground conducting pattern serves as one electrode of a plurality of capacitors.

17. (New) The electronic circuit according to claim 15, wherein the perimeter has six sides and interior angles which are one of 90 degrees and 270 degrees.